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Reinforced, Fast, Low-Power, Six-Channel Digital Isolators

MAX22563-MAX22566

Product Highlights

- AEC-Q100 Qualification for /V Devices
- Reinforced Galvanic Isolation for Digital Signals
 - 20-SSOP with 5.5mm Creepage and Clearance
 - Withstands 3.75kV_{RMS} for 60s (V_{ISO})
 - Continuously Withstands 784V_{RMS} (V_{IOWM})
 - Withstands ±12.8kV Surge Between GNDA and GNDB with 1.2/50µs Waveform
 - High CMTI (50kV/µs, typ)
- Low Power Consumption
 - 0.71mW per Channel at 1Mbps with V_{DD} = 1.8V
 - 1.34mW per Channel at 1Mbps with V_{DD} = 3.3V
 - 3.21mW per Channel at 100Mbps with V_{DD} = 1.8V
- Low Propagation Delay and Low Jitter
 - · Maximum Data Rate Up to 200Mbps
 - Low Propagation Delay 7ns (typ) at V_{DD} = 3.3V
 - Clock Jitter RMS 11.1ps (typ)
- Safety Regulatory Approvals (Pending)
 - UL According to UL1577
 - cUL According to CSA Bulletin 5A
 - VDE 0884-11 Reinforced Insulation

Key Applications

- Automotive
 - · Hybrid Electric Vehicle
 - Chargers
 - Battery Management System (BMS)
 - Inverters

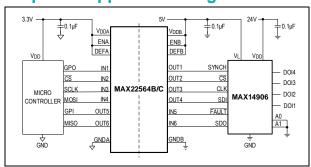
The MAX22563-MAX22566 are a family of 6-channel, reinforced, fast, low-power digital galvanic isolators using Maxim Integrated's proprietary process technology. All devices feature reinforced isolation with a withstand voltage rating of 3.75kV_{RMS} for 60 seconds. Both automotive and general-purpose devices are rated for operation at ambient temperatures from -40°C to +125°C.

Devices with /V suffix are AEC-Q100 qualified. See the <u>Ordering Information</u> for all automotive grade part numbers.

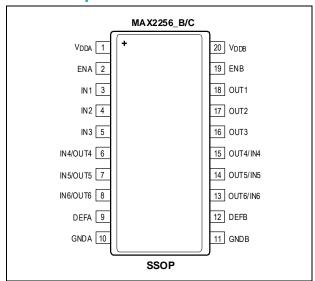
- Industrial
 - Isolated SPI, RS-232/422/485, CAN, Digital I/O
 - · Fieldbus Communications
 - Motor Control
 - · Medical Systems

These devices transfer digital signals between circuits with different power domains, using as little as 0.71mW per channel at 1Mbps (1.8V supply). The low-power feature reduces system dissipation, increases reliability, and enables compact designs.

Simplified Application Diagram



Pin Description



Devices are available with a maximum data rate of either 25Mbps or 200Mbps and with user-selectable default-high or default-low outputs. The devices feature low propagation delay and low clock jitter, which reduces system latency.

Independent 1.71V to 5.5V supplies on each side also make the devices suitable for use as level translators.

The MAX22563 features three channels transmitting signals in one direction and three in opposite; the MAX22564 offers four channels transmitting signals in one direction and two in opposite; the MAX22565 provides five channels transmitting signals in one direction and one in opposite; the MAX22566 features all six channels transmitting signals in one direction.

Ordering Information appears at end of data sheet.

Absolute Maximum Ratings

V _{DDA} to GNDA0.3V to +6V
V _{DDB} to GNDB0.3V to +6V
IN_ on Side A, ENA, DEFA to GNDA0.3V to +6V
IN_ on Side B, ENB, DEFB to GNDB0.3V to +6V
OUT_ on Side A to GNDA0.3V to (V _{DDA} + 0.3V)
OUT_ on Side B to GNDB0.3V to (V_{DDB} + 0.3V)
Short-Circuit Continuous Current
OUT_ on Side A to GNDA ±30mA

OUT_ on Side B to GNDB±30mA
Continuous Power Dissipation ($T_A = +70$ °C)
SSOP (derate 10.60mW/°C above +70°C)848.36mW
Temperature Ratings
Operating Temperature Range40°C to +125°C
Maximum Junction Temperature+150°C
Storage Temperature Range60°C to +150°C
Lead Temperature (soldering, 10s)+300°C
Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

PACKAGE TYPE: 20 SSOP

Package Code	A20MS+7
Outline Number	<u>21-0056</u>
Land Pattern Number	<u>90-0094</u>
THERMAL RESISTANCE, FOUR LAYER BOARD:	
Junction-to-Ambient (θ _{JA})	94.30°C/W
Junction-to-Case Thermal Resistance (θ_{JC})	43.70°C/W

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the
package regardless of RoHS status.

DC Electrical Characteristics

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 1, 3)

PARAMETER	SYMBOL	$ V_{GNDB} = 3.3V$, $V_{GNDA} = V_{GNDB}$, $T_A = -$		MIN	TYP	MAX	UNITS		
SUPPLY VOLTAGE				•					
	V_{DDA}	Relative to GNDA		1.71		5.5	.,		
Supply Voltage	V _{DDB}	Relative to GNDB		1.71		5.5	V		
Undervoltage-Lockout Threshold	V _{UVLO} _	V _{DD} _ rising		1.5	1.6	1.66	V		
Undervoltage-Lockout	V _{UVLO_HYST}				45		mV		
Threshold Hysteresis MAX22563 SUPPLY CU							<u> </u>		
WAX22303 SUPPLI CU	(Note 2)		\/ E \/		1 22	2.20			
			$V_{DDA} = 5V$		1.23	2.28	_		
		500kHz square wave, C _L = 0pF	$V_{DDA} = 3.3V$		1.22	2.25	_		
		wave, CL = Opr	$V_{DDA} = 2.5V$		1.21	2.24	1		
Side A Supply Current	I _{DDA}		V _{DDA} = 1.8V		1.18	1.97	mA		
			$V_{DDA} = 5V$		7.83	10.26	_		
		50MHz square	$V_{DDA} = 3.3V$		6.47	8.71	1		
		wave, $C_L = 0pF$	$V_{DDA} = 2.5V$		5.90	8.03			
			$V_{DDA} = 1.8V$		5.35	7.10			
					$V_{DDB} = 5V$		1.23	2.28	
		500kHz square wave, C _L = 0pF	$V_{DDB} = 3.3V$		1.22	2.25			
	I _{DDB}		$V_{DDB} = 2.5V$		1.21	2.24			
01 0 0 0 0 0			$V_{DDB} = 1.8V$		1.18	1.97			
Side B Supply Current		IDDB		V _{DDB} = 5V		7.83	10.26	mA	
		50MHz square	V _{DDB} = 3.3V		6.47	8.71			
				wave, $C_L = 0pF$	V _{DDB} = 2.5V		5.90	8.03	1
			V _{DDB} = 1.8V		5.35	7.10	-		
MAX22564 SUPPLY CU	RRENT (Note 2)	L	1 000						
			V _{DDA} = 5V		1.09	2.01			
		500kHz square	$V_{DDA} = 3.3V$		1.07	1.99	1		
		wave, $C_L = 0pF$	$V_{DDA} = 2.5V$		1.06	1.98	1		
			$V_{DDA} = 1.8V$		1.04	1.66	1		
Side A Supply Current	I _{DDA}		$V_{DDA} = 5V$		7.63	10.10	mA		
		FOMILE OF LOTE	$V_{DDA} = 3.3V$		6.67	9.01	1		
		50MHz square wave, C _L = 0pF	$V_{DDA} = 3.5V$ $V_{DDA} = 2.5V$		6.28	8.52	1		
		,			5.84	7.67	1		
			V _{DDA} = 1.8V						
			$V_{DDB} = 5V$		1.38	2.55	-		
		500kHz square	V _{DDB} = 3.3V		1.36	2.52	-		
Side B Supply Current	I _{DDB}	wave, C _L = 0pF	V _{DDB} = 2.5V		1.35	2.51	mA		
50MHz square wave, C _L = 0pF		V _{DDB} = 1.8V		1.32	2.28	_			
				$V_{DDB} = 5V$		8.04	10.38	1	
	wave, C _L =	wave, $C_L = 0pF$	$V_{DDB} = 3.3V$		6.27	8.41			

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 1, 3)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS			
			V _{DDB} = 2.5V		5.54	7.53				
			$V_{DDB} = 1.8V$		4.87	6.53				
MAX22565 SUPPLY CUF	RRENT (Note 2)								
			V _{DDA} = 5V		0.94	1.74				
		500kHz square	$V_{DDA} = 3.3V$		0.93	1.72				
		wave, C _L = 0pF	V _{DDA} = 2.5V		0.92	1.71				
Cido A Cumply Current	,		$V_{DDA} = 1.8V$		0.90	1.34	A			
Side A Supply Current	I _{DDA}		V _{DDA} = 5V		7.44	9.96	mA			
		50MHz square	$V_{DDA} = 3.3V$		6.88	9.31				
		wave, C _L = 0pF	$V_{DDA} = 2.5V$		6.64	9.03				
			$V_{DDA} = 1.8V$		6.32	8.23				
			V _{DDB} = 5V		1.53	2.82				
		500kHz square	$V_{DDB} = 3.3V$		1.50	2.79				
		wave, C _L = 0pF	$V_{DDB} = 2.5V$		1.50	2.78				
Cido D. Cumple Cumpant	I _{DDB} 501		$V_{DDB} = 1.8V$		1.45	2.59	A			
Side B Supply Current		IDDB		V _{DDB} = 5V		8.36	10.64	mA		
		50MHz square wave, C _L = 0pF	$V_{DDB} = 3.3V$		6.16	8.19				
			$V_{DDB} = 2.5V$		5.24	7.10				
			$V_{DDB} = 1.8V$		4.45	6.01				
MAX22566 SUPPLY CUF	RRENT (Note 2)	·							
						V _{DDA} = 5V		0.79	1.47	
				500kHz square	$V_{DDA} = 3.3V$		0.78	1.45		
							wave, C _L = 0pF	V _{DDA} = 2.5V		0.78
Cida A Comanho Comana	,		V _{DDA} = 1.8V		0.75	1.02				
Side A Supply Current	I _{DDA}		V _{DDA} = 5V		7.25	9.81	mA			
		50MHz square	$V_{DDA} = 3.3V$		7.08	9.61				
		wave, C _L = 0pF	V _{DDA} = 2.5V		7.00	9.52				
			V _{DDA} = 1.8V		6.78	8.79				
			V _{DDB} = 5V		1.67	3.09				
		500kHz square	V _{DDB} = 3.3V		1.65	3.06				
		wave, C _L = 0pF	V _{DDB} = 2.5V		1.64	3.05				
Sido P Supply Current	I-		V _{DDB} = 1.8V		1.59	2.89	^			
Side B Supply Current	I _{DDB}		V _{DDB} = 5V		8.57	10.81	mA			
		50MHz square	$V_{DDB} = 3.3V$		5.97	7.91				
		wave, C _L = 0pF	V _{DDB} = 2.5V		4.89	6.62				
			V _{DDB} = 1.8V		3.97	5.44				
LOGIC INTERFACE (IN_	, OUT_, EN_, D	 PEF_)								
Input High Voltage	V _{IH}	IN_, EN_, DEF_	2.25V ≤ V _{DD} _ ≤ 5.5V	0.7 x V _{DD}			V			

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 1, 3)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
			1.71V ≤ V _{DD} _ < 2.25V	0.75 x V _{DD}			
Input Low Voltage	V	IN EN DEE	2.25V ≤ V _{DD} ≤ 5.5V			0.8	V
	V_{IL}	IN_, EN_, DEF_	1.71V ≤ V _{DD} _ < 2.25V			0.7	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Input Hysteresis	1/	IN EN DEE	MAX2256_B		410		\/
	V _{HYS} IN_, EN_, DEF_	MAX2256_C		80		mV	
Input Pullup Current	I _{PU}	DEFA = DEFB = hi	igh	-10	-5	-1.5	μΑ
Input Pulldown Current	I _{PD}	DEFA = DEFB = lo	w	1.5	5	10	μΑ
Input Capacitance	C _{IN}	f _{SW} = 1MHz			2		pF
EN_ Pullup Current	I _{PU_EN_}			-10	-5	-1.5	μΑ
DEF_ Pullup Current	I _{PU_DEF} _			-10	-5	-1.5	μΑ
Output Voltage High	V _{OH}	I _{OUT} = -4mA source		V _{DD} 0.4			V
Output Voltage Low	V _{OL}	I _{OUT} = 4mA sink				0.4	V

Dynamic Characteristics - MAX2256_C

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 2, 4)

PARAMETER	SYMBOL	СО	NDITIONS	MIN	TYP	MAX	UNITS	
Common-Mode Transient Immunity	CMTI	IN_ = GND_ or V	DD_ (Note 5)		50		kV/μs	
Mariana Data Data	DD	2.25V ≤ V _{DD} _ ≤ 5	5.5V	200			Mhaa	
Maximum Data Rate	DR _{MAX}	1.71V ≤ V _{DD} _ < 2	2.25V	150			Mbps	
Mainimum Dulan Mindah	DW	IN 45 OUT	2.25V ≤ V _{DD} _ ≤ 5.5V			5		
Minimum Pulse Width	PW _{MIN}	IN_ to OUT_	1.71V ≤ V _{DD} _ < 2.25V			6.67	ns	
			4.5V ≤ V _{DD} _ ≤ 5.5V	4.4	6.2	9.5		
			IN_ to OUT_, C _L = 15pF	3.0V ≤ V _{DD} ≤ 3.6V	4.8	7.0	11.2	
					2.25V ≤ V _{DD} _ ≤ 2.75V	5.3	8.3	14.7
Propagation Delay			1.71V ≤ V _{DD} _ ≤ 1.89V	7.1	12.3	22.1	nc	
(<u>Figure 1</u>)			$4.5V \le V_{DD_{-}} \le 5.5V$	4.6	6.5	9.9	ns	
			$3.0 \text{V} \le \text{V}_{DD} \le 3.6 \text{V}$	5.0	7.3	11.6		
	t _{PHL}	IN_ to OUT_, C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V	5.4	8.5	14.9		
			1.71V ≤ V _{DD} _ ≤ 1.89V	7.2	12.1	21.8		
Pulse Width Distortion			$4.5 \text{V} \le \text{V}_{DD_} \le 5.5 \text{V}$		0.4	2.0		
	Vidth Distortion PWD t _{PLH} - t _{PHL}	Itorus torus	$3.0V \le V_{DD_{\perp}} \le 3.6V$		0.4	2.0	ns	
		2.25V ≤ V _{DD} _ ≤ 2.75V		0.3	2.0			

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 2, 4)

PARAMETER	SYMBOL		$NDA = V_{GNDB}, T_A = +25^{\circ}$	MIN	TYP	MAX	UNITS	
			1.71V ≤ V _{DD} _ ≤ 1.89V		0	2.0		
		4.5V ≤ V _{DD} _ ≤ 5.5			3.7			
		$3.0V \le V_{DD_{-}} \le 3.6$		4.7				
Propagation Delay	^t SPLH	2.25V ≤ V _{DD} _ ≤ 2.	75V			6.9		
		1.71V ≤ V _{DD} _ ≤ 1.	89V			12.1		
Skew Part-to-Part (Same Channel)		4.5V ≤ V _{DD} ≤ 5.5	V			4.0	ns	
(Came Chame)		3.0V ≤ V _{DD} ≤ 3.6	V			4.9		
	^t SPHL	2.25V ≤ V _{DD} _ ≤ 2.	75V			7.0		
		1.71V ≤ V _{DD} ≤ 1.	89V			11.8		
Propagation Delay	t _{SCSLH}	1.71V ≤ V _{DD} _ ≤ 5.	5V			2.0		
Skew Channel-to- Channel (Same Direction) (<i>Figure 1</i>)	^t SCSHL	1.71V ≤ V _{DD} _ ≤ 5.				2.0	ns	
		4.5V ≤ V _{DD} _ ≤ 5.5	V			3.7		
	.	$3.0V \le V_{DD_{-}} \le 3.6$	V			4.7		
Propagation Delay	tscolh	2.25V ≤ V _{DD} _ ≤ 2.	75V		6.9	6.9	1	
Skew Channel-to-		1.71V ≤ V _{DD} _ ≤ 1.			12.1	ns		
Channel (Opposite		4.5V ≤ V _{DD} _ ≤ 5.5			4.0			
Direction)		$3.0V \le V_{DD_{-}} \le 3.6$	V			4.9		
	tscohl	$2.25V \le V_{DD_{-}} \le 2.75V$				7.0		
		1.71V ≤ V _{DD} _ ≤ 1.	89V			11.8		
Peak Eye Diagram Jitter	t _{JIT(PK)}	200Mbps			100		ps	
Clock Jitter RMS	tJCLK(RMS)	500kHz clock inpu	t, rising/falling edges		11.1		ps	
			$4.5V \le V_{DD_{\perp}} \le 5.5V$			0.8		
			$3.0V \le V_{DD_{\perp}} \le 3.6V$			1.1		
Rise Time (<u>Figure 1</u>)	t_{R}	t _R	C _L = 5pF	2.25V ≤ V _{DD} ≤ 2.75V			1.5	ns
			1.71V ≤ V _{DD} ≤ 1.89V			2.4		
			$4.5V \le V_{DD} \le 5.5V$			1.0		
Fall Time			$3.0V \le V_{DD} \le 3.6V$			1.4		
(<u>Figure 1</u>)	t _F	C _L = 5pF	2.25V ≤ V _{DD} ≤ 2.75V			1.9	ns	
			1.71V ≤ V _{DD} _ ≤ 1.89V			3.0		
			$4.5 \text{V} \le \text{V}_{DD_} \le 5.5 \text{V}$			3.9		
Enable to Date Valid		MAX2256_,	$3.0V \le V_{DD} \le 3.6V$			5.9		
Enable to Data Valid (<i>Figure 2</i>)	t _{EN}	EN_ to OUT_, C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V			9.1	ns	
	OL = 15pF		1.71V ≤ V _{DD} _ ≤ 1.89V			15.8		
Enable to Tri-state	tтрі	MAX2256_,	$4.5V \le V_{DD_{-}} \le 5.5V$			6.2	ns	
(<u>Figure 2</u>)	t _{TRI}	EN_ to OUT_,	$3.0V \le V_{DD_{\perp}} \le 3.6V$			8.7		

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 2, 4)

PARAMETER	SYMBOL	C	CONDITIONS			MAX	UNITS
		C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V			11.9	
			1.71V ≤ V _{DD} _ ≤ 1.89V			17.8	

Dynamic Characteristics - MAX2256_B

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 2, 4)

PARAMETER	SYMBOL	СО	MIN	TYP	MAX	UNITS	
Common-Mode Transient Immunity	CMTI	IN_ = GND_ or V	DD_ (Note 5)		50		kV/μs
Maximum Data Rate	DR _{MAX}			25			Mbps
Minimum Pulse Width	PW _{MIN}	IN_ to OUT_				40	ns
Glitch Rejection		IN_ to OUT_		10	17	29	ns
			$4.5V \le V_{DD} \le 5.5V$	16.7	22.6	30.7	
			$3.0V \le V_{DD} \le 3.6V$	17.0	23.4	32.2	
	t _{PLH}	IN_ to OUT_, $C_L = 15pF$	2.25V ≤ V _{DD} _ ≤ 2.75V	17.7	24.8	35.3	
Propagation Delay			1.71V ≤ V _{DD} _ ≤ 1.89V	19.6	28.8	42.8	
(<u>Figure 1</u>)			$4.5 \text{V} \le \text{V}_{DD} \le 5.5 \text{V}$	16.4	22.7	32.1	ns
			$3.0V \le V_{DD_{\perp}} \le 3.6V$	16.8	23.5	33.8	
	t _{PHL}	IN_ to OUT_, $C_L = 15pF$	2.25V ≤ V _{DD} _ ≤ 2.75V	17.3	24.8	36.7	
		1.71V ≤ V _{DD} _ ≤ 1.89V	19.0	28.4	43.7		
	PWD	PWD t _{PLH} - t _{PHL}	4.5V ≤ V _{DD} _ ≤ 5.5V		0.2	4.0	
			$3.0V \le V_{DD_{\perp}} \le 3.6V$		0.2	4.0	
Pulse Width Distortion			2.25V ≤ V _{DD} _ ≤ 2.75V		0.3	4.0	ns
			1.71V ≤ V _{DD} _ ≤ 1.89V		0.6	4.0	
		$4.5V \le V_{DD_{\perp}} \le 5.$	5V			14.0	
	t	$3.0V \le V_{DD_{\perp}} \le 3.0$	6V			13.8	
	^t SPLH	2.25V ≤ V _{DD} _ ≤ 2	2.75V			15.2	
Propagation Delay Skew Part-to-Part		1.71V ≤ V _{DD} _ ≤ 1	.89V			21.9	ns
(Same Channel)		4.5V ≤ V _{DD} _ ≤ 5.	5V			13.0	115
	topu	$3.0V \le V_{DD} \le 3.0$	6V			13.5	
	^t SPHL	2.25V ≤ V _{DD} _ ≤ 2	2.75V			15.4	
		1.71V ≤ V _{DD} _ ≤ 1.89V				21.4	
Propagation Delay	t _{SCSLH}	1.71V ≤ V _{DD} _ ≤ 5	5.5V			4.0	
Skew Channel-to- Channel (Same Direction) (Figure 1)	^t SCSHL	1.71V ≤ V _{DD} _ ≤ 5	5.5V			4.0	ns
	tscolh	4.5V ≤ V _{DD} _ ≤ 5.	5V			14.0	ns

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)}$ (Notes 2, 4)

PARAMETER	SYMBOL		DITIONS	MIN	TYP	MAX	UNITS			
			$3.0V \le V_{DD} \le 3.6V$					13.8		
		2.25V ≤ V _{DD} ≤ 2.75V				15.2				
Propagation Delay		1.71V ≤ V _{DD} _ ≤ 1.89	9V			21.9				
Skew Channel-to- Channel (Opposite		4.5V ≤ V _{DD} _ ≤ 5.5V				13.0				
Direction)		$3.0V \le V_{DD_{\perp}} \le 3.6V$				13.5				
	^t SCOHL	2.25V ≤ V _{DD} _ ≤ 2.75	ōV			15.4				
		1.71V ≤ V _{DD} _ ≤ 1.89	9V			21.4				
Peak Eye Diagram Jitter	t _{JIT(PK)}	25Mbps			250		ps			
			$4.5V \le V_{DD_{\perp}} \le 5.5V$			0.8				
			$3.0V \le V_{DD_{\perp}} \le 3.6V$			1.1				
Rise Time (<u>Figure 1</u>)	t_R $C_L = 5pF$	C _L = 5pF	2.25V ≤ V _{DD} _ ≤ 2.75V			1.5	ns			
		1.71V ≤ V _D 1.89V	1.71V ≤ V _{DD} _ ≤ 1.89V			2.4				
	t _F	tF	t_F $C_L = 5p$		$4.5V \le V_{DD_{-}} \le 5.5V$			1.0		
						$3.0V \le V_{DD_{\perp}} \le 3.6V$			1.4	
Fall Time (<u>Figure 1</u>)				C _L = 5pF	2.25V ≤ V _{DD} _ ≤ 2.75V			1.9	ns	
			1.71V ≤ V _{DD} _ ≤ 1.89V			3.0				
			$4.5V \le V_{DD_{-}} \le 5.5V$			3.9				
		MAX2256_,	$3.0V \le V_{DD_{\perp}} \le 3.6V$			5.9				
Enable to Data Valid (<i>Figure 2</i>)	Data Valid t _{EN}	EN_ to OUT_, $C_1 = 15pF$	$2.25V \le V_{DD_{-}} \le$ $2.75V$			9.1	ns			
		- '	1.71V ≤ V _{DD} _ ≤ 1.89V			15.8				
			4.5V ≤ V _{DD} _ ≤ 5.5V			6.2				
		MAX2256_,	$3.0V \le V_{DD_{-}} \le 3.6V$			8.7				
Enable to Tri-state (Figure 2)	t _{TRI}	t _{TRI} EN_ to OU	EN_ to OUT_, C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V			11.9	ns		
		,	1.71V ≤ V _{DD} _ ≤ 1.89V			17.8				

- Note 1: General purpose devices are 100% production tested at $T_A = +25$ °C. Specifications over temperature are guaranteed by design and characterization. Automotive devices are 100% production tested at $T_A = +25$ °C and $T_A = +125$ °C.
- Note 2: Not production tested. Guaranteed by design and characterization.
- **Note 3:** All currents into the device are positive. All currents out of the device are negative. All voltages are referenced to their respective grounds (GNDA or GNDB), unless otherwise noted.
- **Note 4:** All measurements are taken with $V_{DDA} = V_{DDB}$, unless otherwise noted.
- Note 5: CMTI is the maximum sustainable common-mode voltage slew rate while maintaining the correct output. CMTI applies to both rising and falling common-mode voltage edges. Tested with the transient generator connected between GNDA and GNDB (V_{CM} = 1000V).

ESD Protection

PARAMETER	SYMBOL	CONDITIONS	VALUE	UNITS
ESD		Human Body Model, All Pins	±4	kV
ESD		IEC 61000-4-2 Contact, GNDB to GNDA	±8	kV

Test Circuit and Timing Diagrams

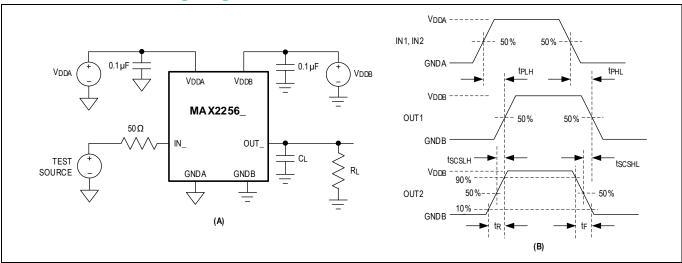


Figure 1. Test Circuit (A) and Timing Diagram (B)

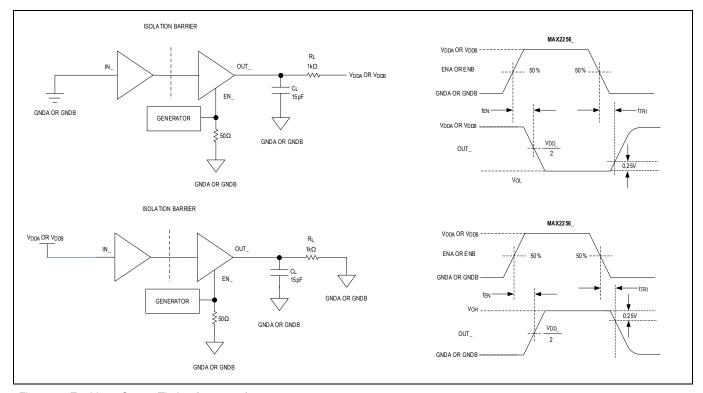


Figure 2. Enable to Output Timing (t_{EN}, t_{TRI})

Table 1. Insulation Characteristics

PARAMETER	SYMBOL	CONDITIONS	VALUE	UNITS
Partial Discharge Test Voltage	V _{PR}	Method B1 = V _{IORM} x 1.875 (t = 1s, partial discharge < 5pC)	2,078	V _P
Maximum Repetitive Peak Isolation Voltage	V _{IORM}	(Note 6)	1,108	V _P
Maximum Working Isolation Voltage	V _{IOWM}	Continuous RMS voltage (Note 6)	784	V _{RMS}
Maximum Transient Isolation Voltage	V _{IOTM}	t = 1s (Note 6)	5,300	V _P
Maximum Withstanding Isolation Voltage	V _{ISO}	f _{SW} = 60Hz, duration = 60s (Notes 6, 7)	3,750	V _{RMS}
Maximum Surge Isolation Voltage	V _{IOSM}	Reinforced Insulation, test method per IEC 60065, V _{TEST} = 1.6 x V _{IOSM} = 12,800V _{PEAK} (Notes 6, 9)	8,000	V _P
		V _{IO} = 500V, T _A = +25°C	>10 ¹²	
Isolation Resistance	R _{IO}	$V_{IO} = 500V, 100^{\circ}C \le T_{A} \le 125^{\circ}C$	>10 ¹¹	Ω
		$V_{IO} = 500V, T_S = 150^{\circ}C$		
Barrier Capacitance Side A to Side B	C _{IO}	f _{SW} = 1MHz (Note 8)	1.5	pF
Minimum Creepage Distance	CPG		5.5	mm
Minimum Clearance Distance	CLR		5.5	mm
Internal Clearance		Distance through insulation	0.021	mm
Comparative Tracking Index	CTI	Material Group II (IEC 60112)	>400	
Climate Category			40/125/21	
Pollution Degree (DIN VDE 0110, Table 1)			2	

Note 6: V_{ISO} , V_{IOWM} , V_{IOTM} , V_{IORM} , and V_{IOSM} are defined by the IEC 60747-5-5 standard.

Note 7: Product is qualified at V_{ISO} for 60s and 100% production tested at 120% of V_{ISO} for 1s.

Note 8: Capacitance is measured with all pins on the A side and B side tied together.

Note 9: Devices are immersed in oil during surge characterization.

Safety Regulatory Approvals (Pending)

UL

The MAX22563-MAX22566 are certified under UL1577. For more details, refer to File E351759.

Rated up to $3750 V_{\mbox{RMS}}$ isolation voltage for single protection.

cUL (Equivalent to CSA notice 5A)

The MAX22563-MAX22566 are certified up to $3750V_{RMS}$ for single protection. For more details, refer to File E351759.

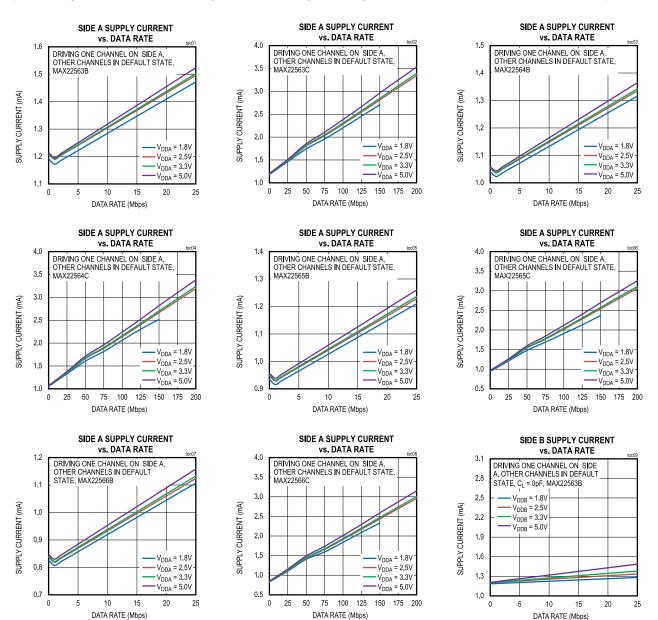
VDE

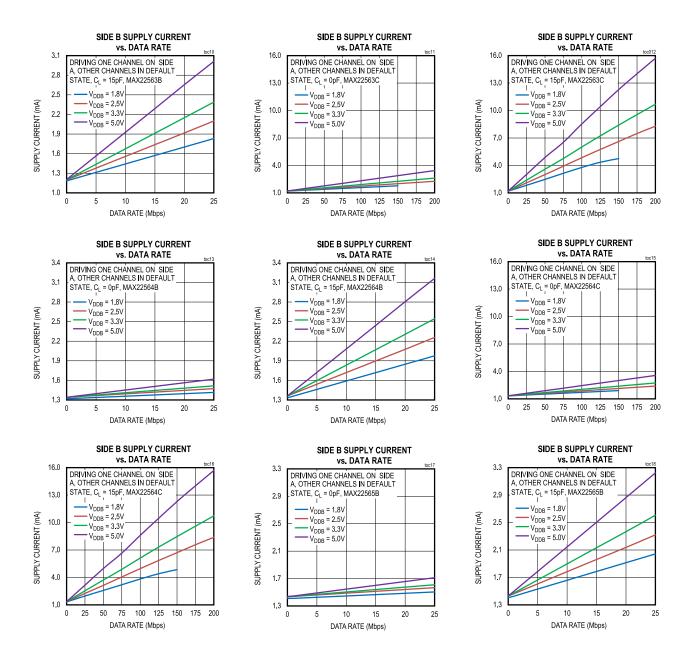
The MAX22563-MAX22566 are certified to DIN VDE V 0884-11: 2017-1. Reinforced Insulation, Maximum Transient Isolation Voltage $5300V_{PK}$, Maximum Repetitive Peak Isolation Voltage $1108V_{PK}$.

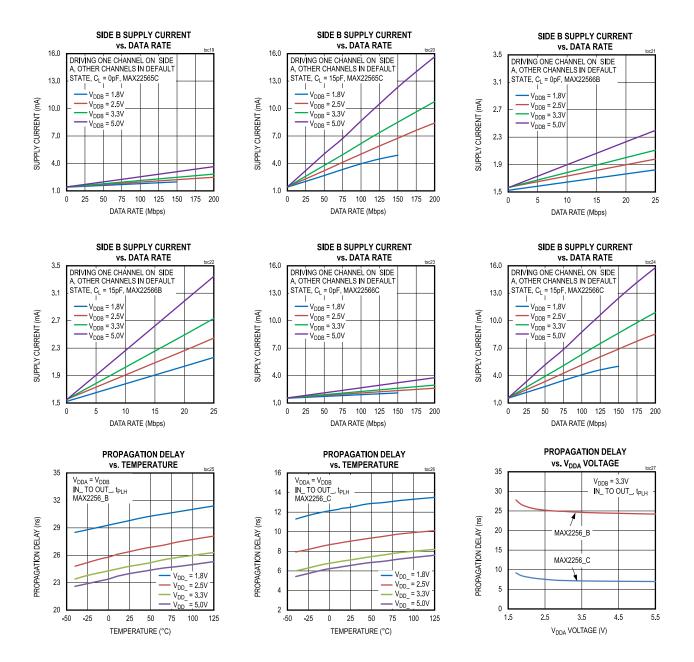
These couplers are suitable for "safe electrical insulation" only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

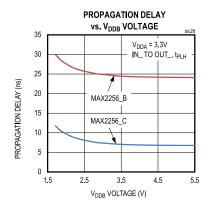
Typical Operating Characteristics

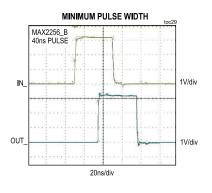
 $(V_{DDA} - V_{GNDA} = +3.3V, V_{DDB} - V_{GNDB} = +3.3V, V_{GNDA} = V_{GNDB}, T_A = +25$ °C, unless otherwise noted.)

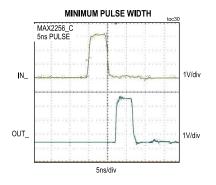


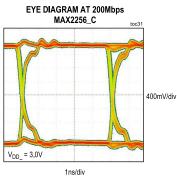


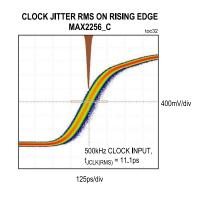


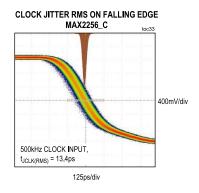


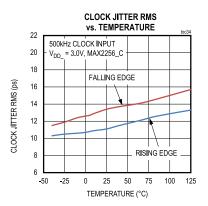




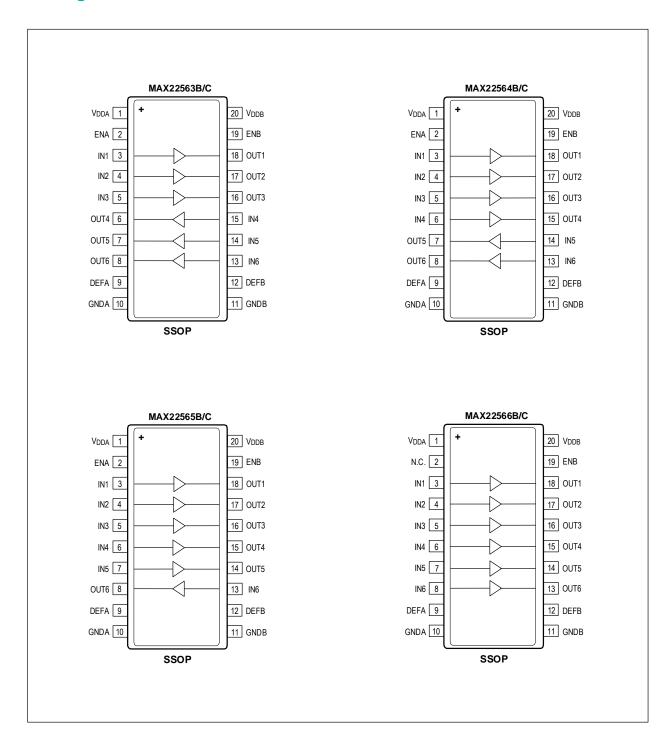








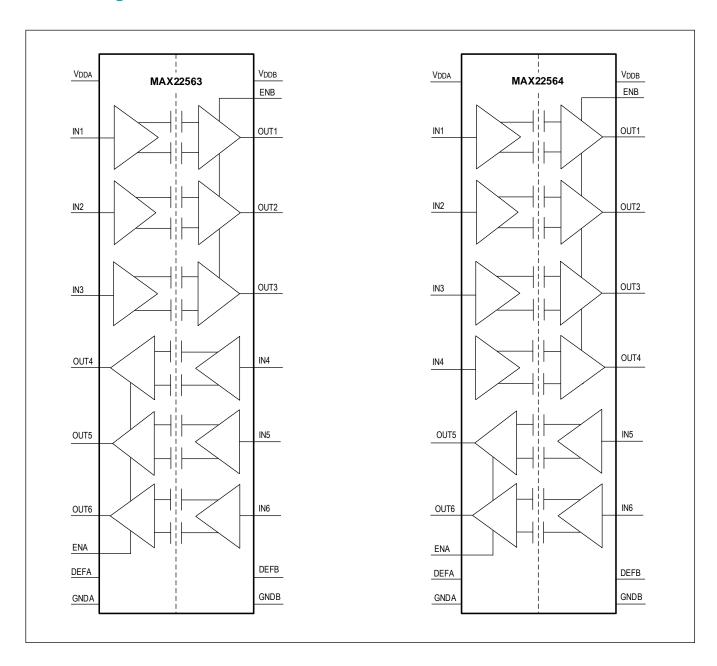
Pin Configurations

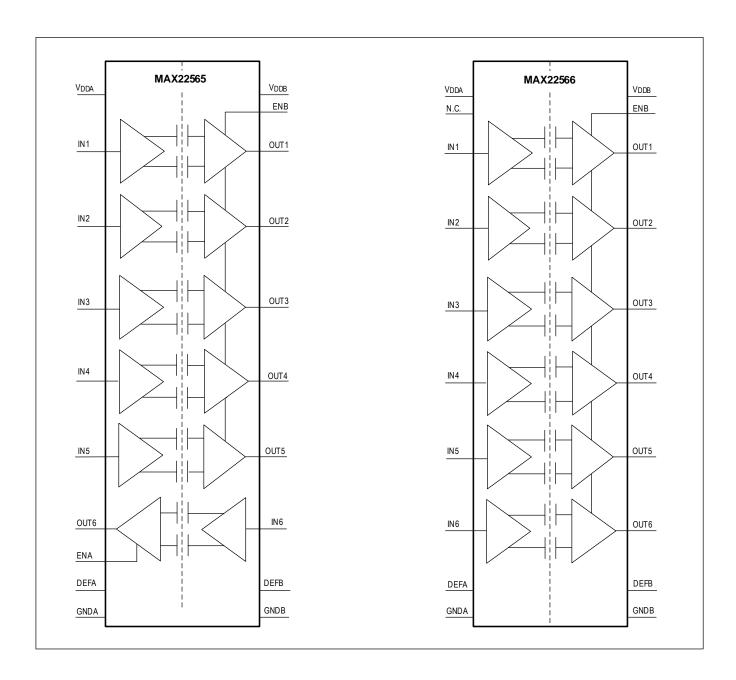


Pin Descriptions

	P	IN			T. W.O.T.O.V.		
MAX22563	MAX22564	IAX22564 MAX22565 MAX22566		NAME	FUNCTION		
1	1	1	1	V _{DDA}	Power Supply Input for Side A. Bypass V _{DDA} to GNDA with a 0.1µF ceramic capacitor as close as possible to the pin.		
-	-	_	2	N.C.	Not Connected. Not internally connected.		
2	2	2	-	ENA	Active-High Enable for Side A. ENA has an internal $5\mu A$ pullup to V_{DDA} .		
3	3	3	3	IN1	Logic Input 1 on Side A. Corresponds to Logic Output 1 on Side B.		
4	4	4	4	IN2	Logic Input 2 on Side A. Corresponds to Logic Output 2 on Side B.		
5	5	5	5	IN3	Logic Input 3 on Side A. Corresponds to Logic Output 3 on Side B.		
15	6	6	6	IN4	Logic Input 4 on Side A/B. Corresponds to Logic Output 4 on Side B/A.		
14	14	7	7	IN5	Logic Input 5 on Side A/B. Corresponds to Logic Output 5 on Side B/A.		
13	13	13	8	IN6	Logic Input 6 on Side A/B. Corresponds to Logic Output 6 on Side B/A.		
9	9	9	9	DEFA	Default Control Input for Side A. Connect DEFA to V _{DDA} to set side A outputs to default-high state and to enable the pullup current on side A inputs. Connect DEFA to GNDA to set side A outputs to a default-low state and enable the pulldown current on side A inputs. DEFA must be tied to the same state (high or low) as DEFB.		
10	10	10	10	GNDA	Ground Reference for Side A.		
11	11	11	11	GNDB	Ground Reference for Side B.		
12	12	12	12	DEFB	Default Control Input for Side B. Connect DEFB to V _{DDB} to set side B outputs to a default-high state and to enable the pullup current on side B inputs. Connect DEFB to GNDB to set side B outputs to default-low state and enable the pulldown current on side B inputs. DEFB must be tied to the same state (high or low) as DEFA.		
8	8	8	13	OUT6	Logic Output 6 on Side B/A. OUT6 is the logic output for the IN6 input on Side A/B.		
7	7	14	14	OUT5	Logic Output 5 on Side B/A. OUT5 is the logic output for the IN5 input on Side A/B.		
6	15	15	15	OUT4	Logic Output 4 on Side B/A. OUT4 is the logic output for the IN4 input on Side A/B.		
16	16	16	16	OUT3	Logic Output 3 on Side B. OUT3 is the logic output for the IN3 input on Side A.		
17	17	17	17	OUT2	Logic Output 2 on Side B. OUT2 is the logic output for the IN2 input on Side A.		
18	18	18	18	OUT1	Logic Output 1 on Side B. OUT1 is the logic output for the IN1 input on Side A.		
19	19	19	19	ENB	Active-High Enable for Side B. ENB has an internal 5µA pullup to V _{DDB} .		
20	20	20	20	V _{DDB}	Power Supply Input for Side B. Bypass V _{DDB} to GNDB with a 0.1µF ceramic capacitor as close as possible to the pin.		

Functional Diagrams





Detailed Description

The MAX22563-MAX22566 are a family of 6-channel reinforced digital isolators in a compact 20-SSOP package, with an isolation rating of 3.75kV_{RMS}. This family of devices offers all possible unidirectional channel configurations to accommodate any 6-channel design.

The MAX22563 features three channels transmitting digital signals in one direction and three channels transmitting in the opposite direction for applications such as an isolated micro-controller interface. The MAX22564 offers four channels transmitting digital signals in one direction and two channels transmitting in the opposite direction, making it an ideal candidate for applications such as isolated SPI. The MAX22565 provides five channels transmitting digital signals in one direction and one channel transmitting in the opposite direction. The MAX22566 features all six channels transmitting digital signals in one direction, which is suitable in applications such as isolated digital I/O.

The MAX22563-MAX22566 are available in a 20-pin SSOP package with 5.5mm creepage and clearance, with an isolation rating of 3.75kV_{RMS}. This family of digital isolators offers low-power operation, high electromagnetic interference (EMI) immunity, and stable temperature performance through Maxim Integrated's proprietary process technology. The devices isolate different ground domains and block high-voltage/high-current transients from sensitive or human interface circuitry.

The devices are available with a maximum data rate of either 25Mbps (B version) or 200Mbps (C version). All devices feature user-selectable default-high or default-low outputs. The default is the state the output assumes when the input is not powered or if the input is open-circuit. The MAX22563-MAX22566 have two supply inputs (V_{DDA} and V_{DDB}) that independently set the logic levels on either side of the device. V_{DDA} and V_{DDB} are referenced to GNDA and GNDB, respectively. The MAX22563-MAX22566 also feature a refresh circuit to ensure output accuracy when an input remains in the same state indefinitely.

Digital Isolation

The family of devices provides reinforced galvanic isolation for digital signals that are transmitted between two ground domains. The MAX22563-MAX22566 can withstand differences of up to $3.75kV_{RMS}$ for up to 60 seconds, and up to $1108V_{PFAK}$ of continuous isolation.

AEC-Q100 Qualification

Devices with /V suffix are AEC-Q100 qualified. See the Ordering Information for all automotive grade part numbers.

Level Shifting

The wide supply voltage range of both V_{DDA} and V_{DDB} allows the MAX22563-MAX22566 to be used for level translation in addition to isolation. V_{DDA} and V_{DDB} can be independently set to any voltage from 1.71V to 5.5V. The supply voltage sets the logic level on the corresponding side of the isolator.

Unidirectional Channels

Each channel of the device is unidirectional; it only passes data in one direction, as indicated in the <u>Functional Diagram</u>. All devices feature six unidirectional channels that operate independently with guaranteed data rates from DC to 25Mbps (B version), or from DC to 200Mbps (C version). The output driver of each channel is push-pull, eliminating the need for pullup resistors. The outputs are able to drive both TTL and CMOS logic inputs.

Startup and Undervoltage-Lockout

The V_{DDA} and V_{DDB} supplies are both internally monitored for undervoltage conditions. Undervoltage events can occur during power-up, power-down, or during normal operation due to a sagging supply voltage. When an undervoltage condition is detected on either supply, all outputs go to their default states regardless of the state of the inputs as seen in <u>Table 2</u>. <u>Figure 3</u> through <u>Figure 6</u> show the behavior of the outputs during power-up and power-down.

Table 2. Output Behavior During Undervoltage Conditions

V _{IN} _	V_{DDA}	V_{DDB}	ENA, ENB	V _{OUTA}	V _{OUTB}	
1	Doward	Powered	1	High	High	
'	Powered	Powered	0	Hi-Z	Hi-Z	
	Powered	Dowered	1	Low	Low	
0		Powered	0	Hi-Z	Hi-Z	
	Undervoltage	Indervoltage Powered	1	Default	Default	
X			0	Hi-Z	Hi-Z	
V	Powered	Powered Undervoltage	l lo dominito do	1	Default	Default
X			0	Hi-Z	Hi-Z	

Note: "X" is don't care.

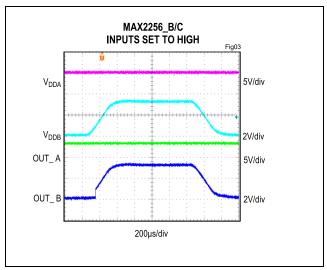


Figure 3. Undervoltage Lockout Behavior, Default sets to High, Inputs set to High

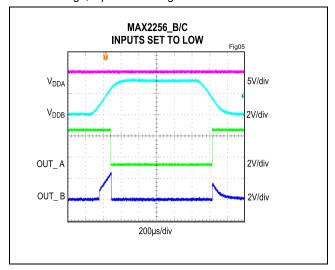


Figure 5. Undervoltage Lockout Behavior, Default sets to High, Inputs set to Low

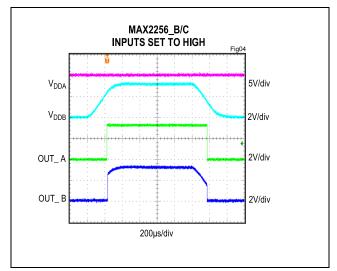


Figure 4. Undervoltage Lockout Behavior, Default sets to Low, Inputs set to High

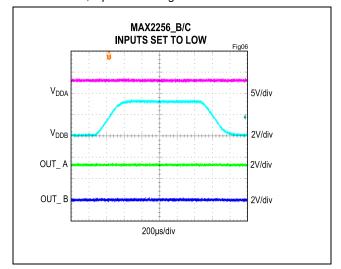


Figure 6. Undervoltage Lockout Behavior, Default sets to Low, Inputs set to Low

Selectable Output Default (DEFA, DEFB)

The default is the state the output assumes when the input is not powered or if the input is open-circuit. The MAX22563-MAX22566 feature user-selectable default-high or default-low outputs. Tie both DEFA and DEFB high to set all channels to default-low.

Ensure the logic state (high or low) of DEFA is the same as that of DEFB. Do not toggle DEFA or DEFB during normal operation.

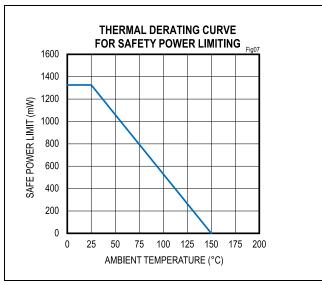
Safety Limit

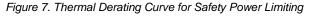
Damage to the IC can result in a low-resistance path to ground or to the supply and, without current limiting, the MAX22563-MAX22566 can dissipate excessive amounts of power. Excessive power dissipation can damage the die and result in damage to the isolation barrier, potentially causing downstream issues. <u>Table 3</u> shows the safety limits for the MAX22563-MAX22566.

The maximum safety temperature (T_S) for the device is the 150°C maximum junction temperature specified in the <u>Absolute Maximum Ratings</u>. The power dissipation (P_D) and junction-to-ambient thermal impedance (θ_{JA}) determine the junction temperature. Thermal impedance values (θ_{JA} and θ_{JC}) are available in the <u>Package Information</u> section and power dissipation calculations are discussed in the <u>Calculating Power Dissipation</u> section. Calculate the junction temperature (T_J) as:

$$T_J = T_A + (P_D \times \theta_{JA})$$

<u>Figure 7</u> shows the thermal derating curve for safety limiting the power of the devices, and <u>Figure 8</u> shows the thermal derating curve for safety limiting the current of the devices. Ensure that the junction temperature does not exceed 150°C.





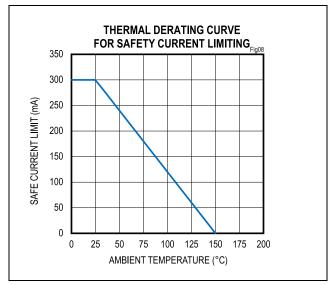


Figure 8. Thermal Derating Curve for Safety Current Limiting

Table 3. Safety Limiting Values

PARAMETER	SYMBOL	TEST CONDITIONS	MAX	UNIT
Safety Current on Any Pin (No Damage to Isolation Barrier)	IS	T _J = 150°C, T _A = 25°C	300	mA
Total Safety Power Dissipation	P_{S}	T _J = 150°C, T _A = 25°C	1326	mW
Maximum Safety Temperature	T _S		150	°C

Applications Information

Power-Supply Sequencing

The MAX22563-MAX22566 do not require any special power supply sequencing. The logic levels are set independently on either side by V_{DDA} and V_{DDB} . Each supply can be present over the entire specified range regardless of the level or presence of the other supply.

Power-Supply Decoupling

To reduce ripple and the chance of introducing data errors, bypass V_{DDA} and V_{DDB} with $0.1\mu F$ low-ESR ceramic capacitors to GNDA and GNDB, respectively. Place the bypass capacitors as close to the power supply input pins as possible.

Layout Considerations

The PCB designer should follow some critical recommendations in order to get the best performance from the design.

- Keep the input/output traces as short as possible. To keep signal paths low-inductance, avoid using vias.
- Have a solid ground plane underneath the high-speed signal layer.
- Keep the area underneath the devices free from ground and signal planes. Any galvanic or metallic connection between Side A and Side B defeats the isolation.

Calculating Power Dissipation

The required current for a given supply (V_{DDA} or V_{DDB}) can be estimated by summing the current required for each channel. The supply current for a channel depends on whether the channel is an input or an output, the channel's data rate, and the capacitive or resistive load if it is an output. The typical current for an input or output at any data rate can be estimated from the graphs in *Figure 9* and *Figure 10*. Note that the data in *Figure 9* and *Figure 10* are extrapolated from the supply current measurements in a typical operating condition.

The total current for a single channel is the sum of the no load current (shown in <u>Figure 9</u> and <u>Figure 10</u>) which is a function of voltage and data rate, and the load current, which depends on the type of load. Current into a capacitive load is a function of the load capacitance, the switching frequency, and the supply voltage.

$$I_{CL} = C_L \times f_{SW} \times V_{DD}$$

where:

ICI is the current required to drive the capacitive load.

C_I is the load capacitance on the isolator's output pin.

f_{SW} is the switching frequency (bits per second/2).

V_{DD} is the supply voltage on the output side of the isolator.

Current into a resistive load depends on the load resistance, the supply voltage and the average duty cycle of the data waveform. The DC load current can be conservatively estimated by assuming the output is always high.

$$I_{RL} = V_{DD}/R_{L}$$

where:

IRI is the current required to drive the resistive load.

V_{DD} is the supply voltage on the output side of the isolator.

R_I is the load resistance on the isolator's output pin.

Example (shown in <u>Figure 11</u>): A MAX22564C is operating with $V_{DDA} = 2.5V$, $V_{DDB} = 3.3V$, channel 1 operating at 20Mbps with a 15kΩ resistive load; channel 2 operating at 100Mbps with a 10pF capacitive load; channel 3 is not in use and the resistive load is negligible since the isolator is driving a CMOS input; channel 4 held high with a 10kΩ resistive load; channel 5 operating at 50Mbps with a 20kΩ resistive load; and channel 6 operating at 200Mbps with a 15pF capacitive load. See <u>Table 4</u> and <u>Table 5</u> for V_{DDA} and V_{DDB} supply current calculation worksheets.

V_{DDA} must supply (with $V_{DDA} = 2.5V$):

- Channel 1 is an input channel operating at 2.5V and 20Mbps, consuming 0.35mA, estimated from <u>Figure 9</u>.
- Channel 2 is an input channel operating at 2.5V and 100Mbps, consuming 1.19mA, estimated from Figure 9.
- Channels 3 and 4 are input channels operating at 2.5V with DC signal, consuming 0.14mA, estimated from <u>Figure 9</u>.
- Channel 5 is an output channel operating at 2.5V and 50Mbps, consuming 0.52mA, estimated from <u>Figure 10</u>.
- I_{R1} on channel 5 for 20kΩ resistive load at 2.5V and switching at 50Mbps with 50% duty cycle is 0.0625mA.
- Channel 6 is an output channel operating at 2.5V and 200Mbps, consuming 1.31mA, estimated from <u>Figure 10</u>.
- I_{CL} on channel 6 for 15pF capacitive load at 2.5V and 200Mbps is 3.75mA.

Total current for Side A = 7.46mA (typ).

V_{DDB} must supply (with $V_{DDB} = 3.3V$):

- Channel 1 is an output channel operating at 3.3V and 20Mbps, consuming 0.40mA, estimated from Figure 10.
- I_{RL} on channel 1 for 15k Ω resistive load at 3.3V and switching at 20Mbps with 50% duty cycle is 0.11mA.
- Channel 2 is an output channel operating at 3.3V and 100Mbps, consuming 0.96mA, estimated from Figure 10.
- I_{CL} on channel 2 for 10pF capacitive load at 3.3V and 100Mbps is 1.65mA.
- Channels 3 and 4 are output channels operating at 3.3V with DC signal, consuming 0.26mA, estimated from <u>Figure 10</u>.
- I_{RL} on channel 4 for 10kΩ resistive load held at 3.3V is 0.33mA.
- Channel 5 is an input channel operating at 3.3V and 50Mbps, consuming 0.68mA, estimated from Figure 9.
- Channel 6 is an input channel operating at 3.3V and 200Mbps, consuming 2.29mA, estimated from <u>Figure 9</u>. Total current for Side B = 6.94mA (typ).

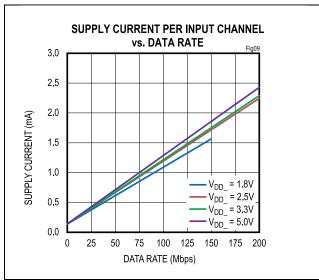


Figure 9. Supply Current Per Input Channel (Calculated)

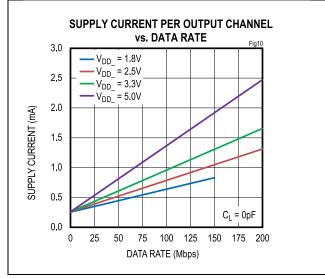


Figure 10. Supply Current Per Output Channel (Calculated)

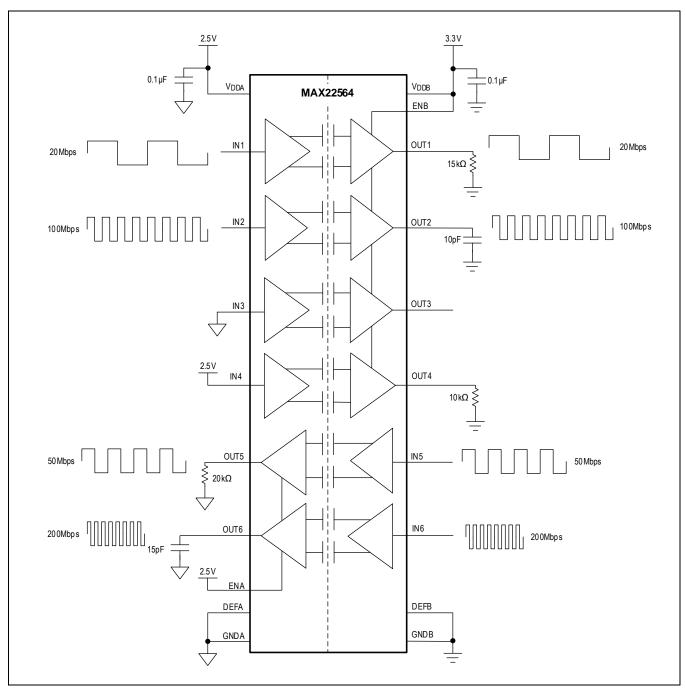


Figure 11. Example Circuit for Supply Current Calculation

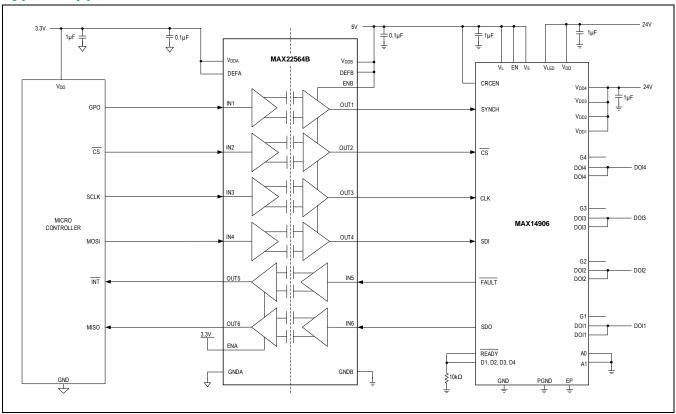
Table 4. Side A Supply Current Calculation Worksheet

SIDE A	V _{DDA} = 2.5V						
CHANNEL	IN/OUT	DATA RATE (Mbps)	LOAD TYPE	OAD TYPE LOAD "NO LOAD CURRENT (r		LOAD CURRENT (mA)	
1	IN	20			0.35		
2	IN	100			1.19		
3	IN	0			0.14		
4	IN	0			0.14		
5	OUT	50	Resistive	20kΩ	0.52	2.5V/20kΩ x 0.5 = 0.0625mA	
6	OUT	200	Capacitive	15pF	1.31	2.5V x 100MHz x 15pF = 3.75mA	
	Total: 7.46mA						

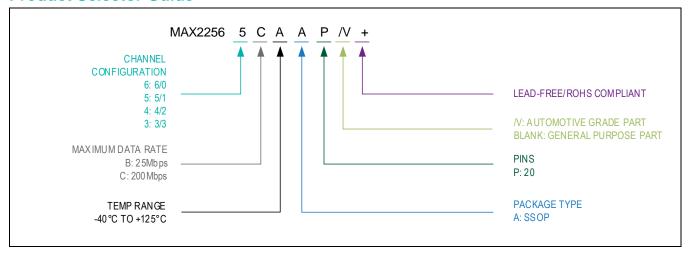
Table 5. Side B Supply Current Calculation Worksheet

SIDE B	V _{DDB} = 3.3V							
CHANNEL	L IN/OUT DATA RATE (Mbps) LOAD		LOAD TYPE	TYPE LOAD "NO LOAD" CURRENT (mA)		LOAD CURRENT (mA)		
1	OUT	20	Resistive	15kΩ	0.40	$3.3V/15k\Omega \times 0.5 = 0.11mA$		
2	OUT	100	Capacitive	10pF	0.96	3.3V x 50MHz x 10pF = 1.65mA		
3	OUT	0			0.26			
4	OUT	0	Resistive	10kΩ	0.26	$3.3V/10k\Omega = 0.33mA$		
5	IN	50			0.68			
6	IN	200			2.29			
_	Total: 6.94mA							

Typical Application Circuit



Product Selector Guide



Ordering Information

PART NUMBER	CHANNEL CONFIGURATION	DATA RATE	DEFAULT OUTPUT	ISOLATION	TEMPERATURE	PIN- PACKAGE
GENERAL PURPOSE		(Mbps)	OUTPUT	VOLTAGE (kV _{RMS})	RANGE (°C)	PACKAGE
MAX22563BAAP+*	3/3	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22563CAAP+*	3/3	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22564BAAP+*	4/2	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22564CAAP+*	4/2	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22565BAAP+*	5/1	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22565CAAP+	5/1	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22566BAAP+*	6/0	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22566CAAP+*	6/0	200	Selectable	3.75	-40 to +125	20-SSOP
AUTOMOTIVE DEVICE	S					•
MAX22563BAAP/V+*	3/3	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22563CAAP/V+*	3/3	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22564BAAP/V+*	4/2	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22564CAAP/V+*	4/2	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22565BAAP/V+*	5/1	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22565CAAP/V+*	5/1	200	Selectable	3.75	-40 to +125	20-SSOP
MAX22566BAAP/V+*	6/0	25	Selectable	3.75	-40 to +125	20-SSOP
MAX22566CAAP/V+*	6/0	200	Selectable	3.75	-40 to +125	20-SSOP

^{*}Future product—contact factory for availability.

Chip Information

PROCESS: BiCMOS

⁺Denotes a lead (Pb)-free/RoHS-compliant package.

[/]V Denotes an automotive qualified part.

MAX22563-MAX22566

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	
0	9/21	Release for Market Intro	_

For pricing, delivery, and ordering information, please visit Maxim Integrated's online storefront at https://www.maximintegrated.com/en/storefront/storefront.html.

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